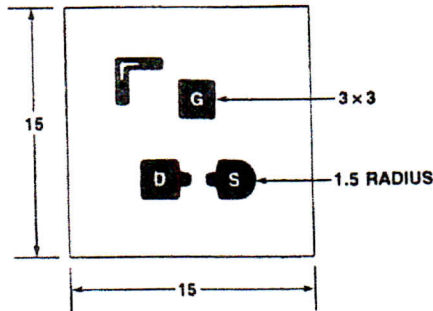




# Sierra Components, Inc.

2222 Park Place • Suite 3E • Minden, Nevada 89423  
Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Aluminum**  
**Backside Material: Gold**  
**Bond Pad Size: .004" X .004" min.**  
**Backside Potential: Drain**  
**Mask Ref: 5007**

**APPROVED BY: DK**

**DIE SIZE .015 Squ."**

**DATE: 6/2/16**

**MFG: Calogic**

**THICKNESS .010"**

**P/N: XPAD-5**